

N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY

V_{DSS}	40V
$R_{DS(ON)(MAX)}$	0.0015 Ω
I_D	240A

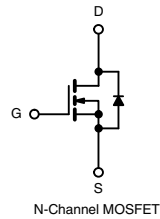
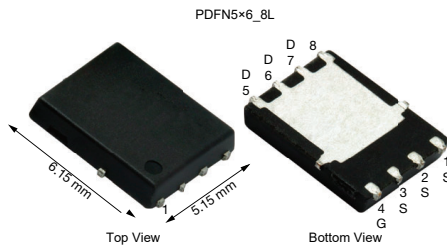
FEATURES

- SGT Power MOSFET
- 175 °C Junction Temperature
- 100 % R_g Tested
- 100 % UIS Tested



APPLICATIONS

- Load Switch
- PWM Application
- Power Management



Absolute Maximum Ratings ($T_c = 25\text{ }^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V_{DS}	40	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current @ 10V	I_D	$T_c = 25\text{ }^\circ\text{C}$	240	A
		$T_c = 100\text{ }^\circ\text{C}$	151	
Pulsed Drain Current	I_{DM}	960	A	
Single Pulse Avalanche Energy	E_{AS}	600	mJ	
Total Power Dissipation	P_D	$T_c = 25\text{ }^\circ\text{C}$	113.6	W
		$T_c = 100\text{ }^\circ\text{C}$	55	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$	

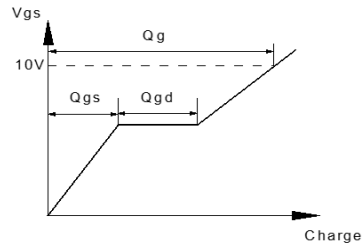
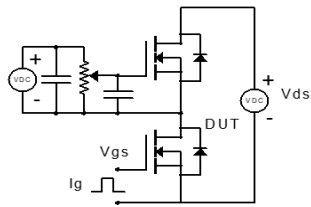
Thermal Characteristics

Parameter	Symbol	TYP.	MAX.	Unit
Thermal resistance, junction-to-ambient	$R_{\theta JA}$	45	52	$^\circ\text{C/W}$
Thermal resistance, junction-to-case	$R_{\theta JC}$	0.9	1.1	

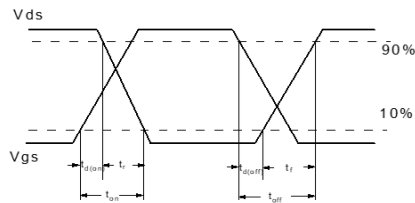
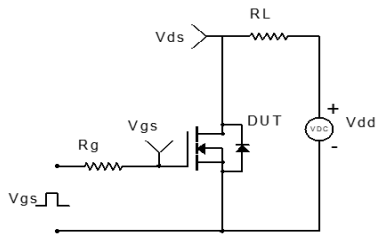
Electrical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	40	-	-	V	
Gate-body Leakage current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	$T_J = 25^\circ\text{C}$	I_{DSS}	$V_{DS} = 32\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	μA
	$T_J = 55^\circ\text{C}$			-	-	5	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	1		2.5	V	
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$	-	0.0012	0.00156	Ω	
		$V_{GS} = 4.5\text{ V}, I_D = 10\text{ A}$	-	0.0015	0.00195		
Forward Transconductance	g_{fs}	$V_{DS} = 5\text{ V}, I_D = 20\text{ A}$	-	62	-	S	
Dynamic Characteristics							
Input Capacitance	C_{iss}	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	8561	-	pF	
Output Capacitance	C_{oss}		-	1288	-		
Reverse Transfer Capacitance	C_{rss}		-	1253	-		
Switching Characteristics							
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}, V_{DS} = 20\text{ V}, I_D = 20\text{ A}$	-	73	-	nC	
Gate-Source Charge	Q_{gs}		-	45	-		
Gate-Drain Charge	Q_{gd}		-	24	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 20\text{ V}, R_L = 1\ \Omega, V_{GEN} = 10\text{ V}, R_G = 6\ \Omega$	-	22	-	nS	
Rise Time	t_r		-	39	-		
Turn-Off Delay Time	$t_{d(off)}$		-	62	-		
Fall Time	t_f		-	30	-		
Drain-Source Body Diode Characteristics							
Diode Forward Voltage	V_{SD}	$I_S = 1\text{ A}, V_{GS} = 0\text{ V}$	-	0.7	1	V	
Continuous Source-Drain Diode Current	I_S	$T_J = 25^\circ\text{C}$	-	-	138	A	
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = 20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	-	77	-	ns	
Reverse Recovery Charge	Q_{rr}		-	69	-	nC	

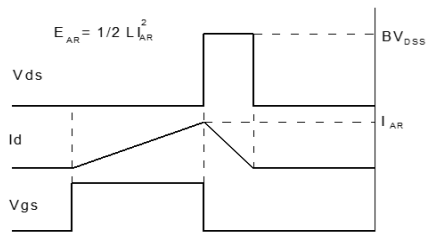
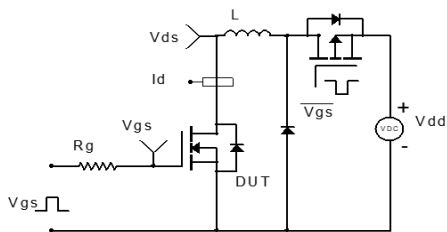
- a. Computed continuous current assumes the condition of T_{J_Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.
- b. This single-pulse measurement was taken under $T_{J_Max} = 150^\circ\text{C}$.
- c. EAS of 600mJ is based on starting $T_J = 25^\circ\text{C}, L = 3.0\text{mH}, I_{AS} = 20\text{A}, V_{GS} = 10\text{V}, V_{DD} = 20\text{V}; 100\%$ test at $L = 0.5\text{mH}, I_{AS} = 42\text{A}$.
- d. The power dissipation PD is based on $T_{J_Max} = 150^\circ\text{C}$.
- e. This value is guaranteed by design hence it is not included in the production test.



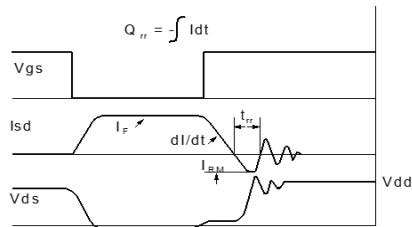
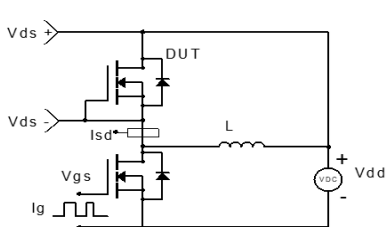
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform

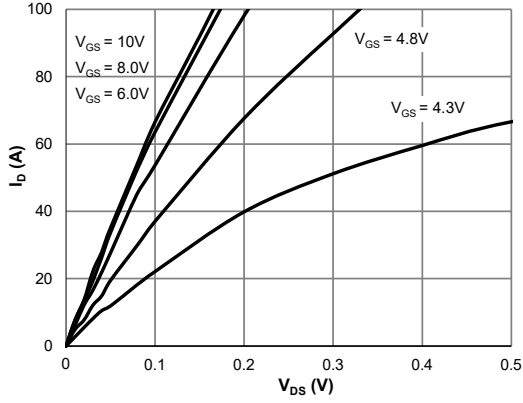


Unclamped Inductive Switching Test Circuit & Waveform

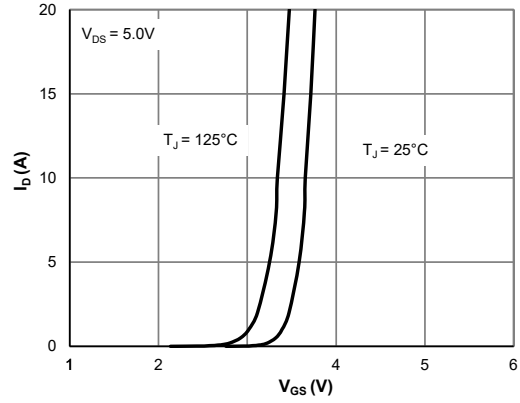


Diode Recovery Test Circuit & Waveform

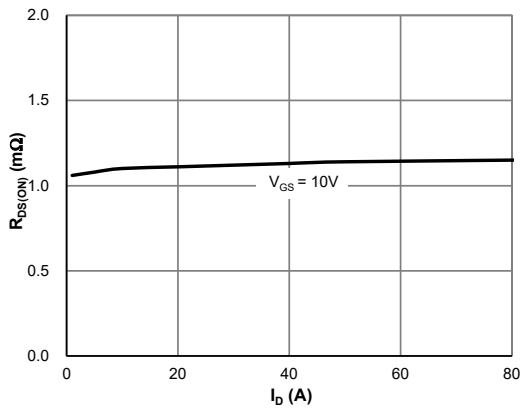
TYPICAL CHARACTERISTICS (25 °C unless noted)



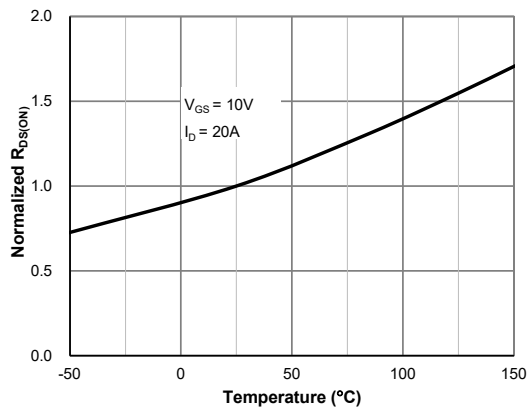
Saturation Characteristics



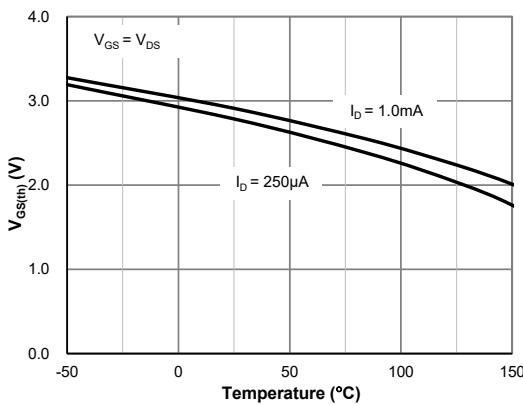
Transfer Characteristics



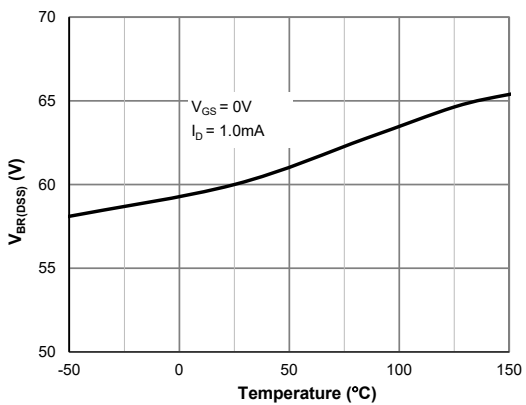
$R_{DS(on)}$ vs. Drain Current



$R_{DS(on)}$ vs. Junction Temperature

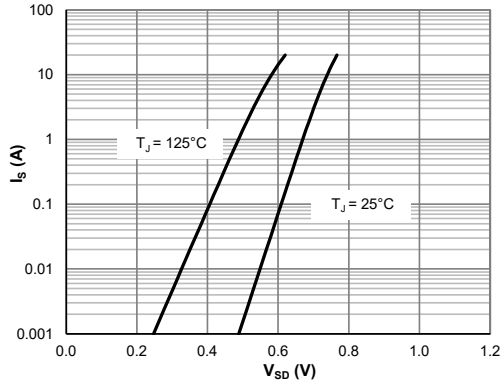


$V_{GS(th)}$ vs. Junction Temperature

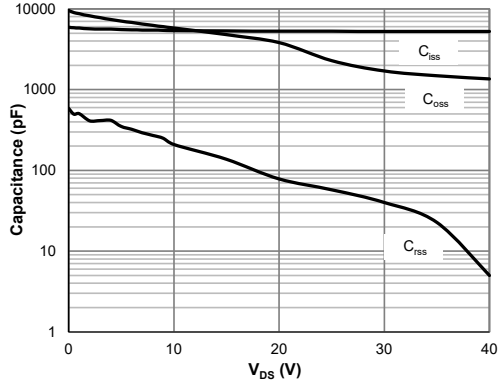


$V_{BR(DSS)}$ vs. Junction Temperature

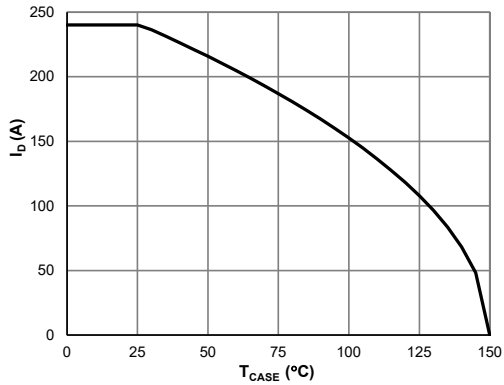
TYPICAL CHARACTERISTICS (25 °C unless noted)



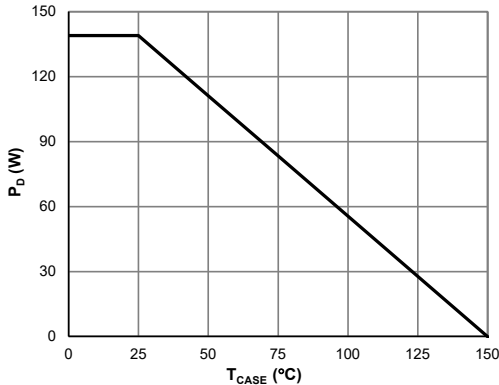
Body-Diode Characteristics



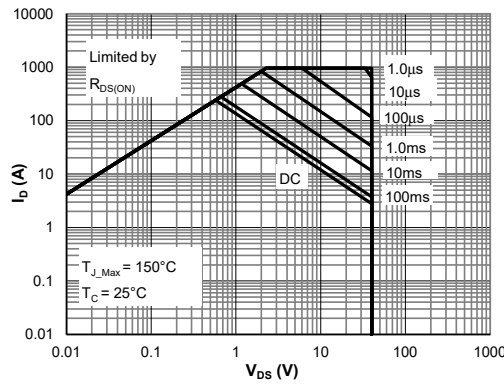
Capacitance Characteristics



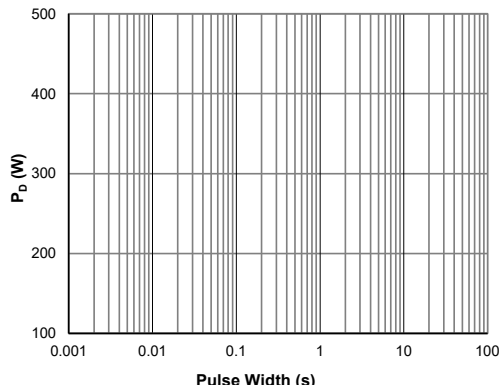
Current De-rating



Power De-rating

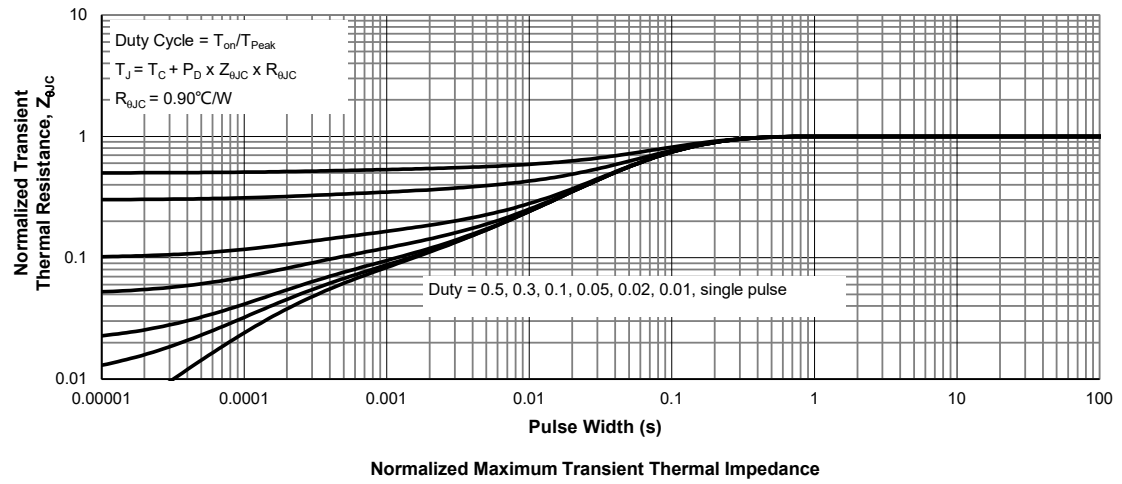


Maximum Safe Operating Area

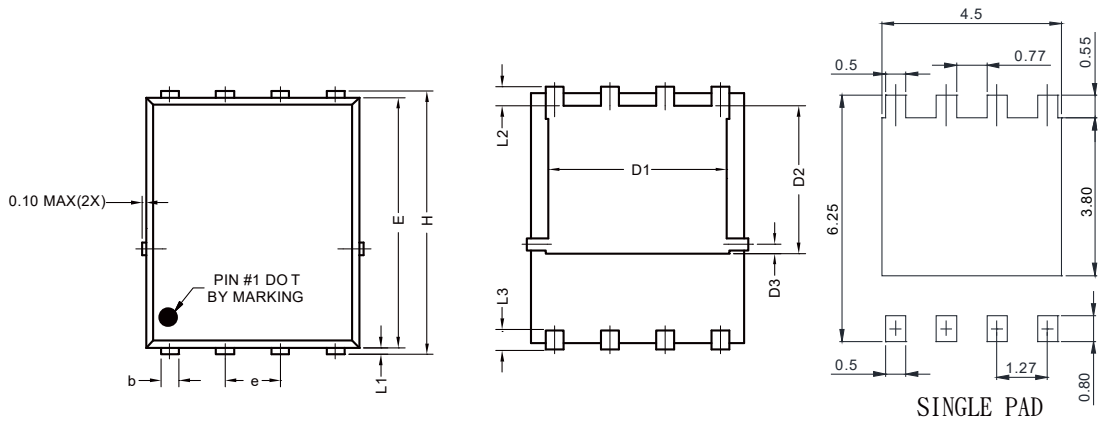


Single Pulse Power Rating, Junction-to-Case

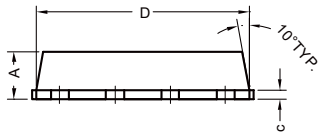
TYPICAL CHARACTERISTICS (25 °C unless noted)



PDFN5x6-8L_EP1_P PACKAGE OUTLIN



RECOMMENDED LAND PATTERN



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.800	1.170	0.031	0.046
b	0.340	0.490	0.013	0.019
c	0.20	0.34	0.008	0.013
D	4.800	5.100	0.009	0.011
D1	3.800	4.200	0.150	0.165
D2	3.180	3.78	0.125	0.149
D3	0.150	0.360	0.006	0.142
E	5.650	5.900	0.222	0.232
e	1.270 TYP		0.050 TYP	
H	5.900	6.150	0.232	0.242
L1	0.050	0.250	0.002	0.010
L2	0.380	0.620	0.015	0.024
L3	0.380	0.75	0.015	0.030